

### REMARKS

In the response to the previous office action, it was contended that the cited reference does not teach a conductive pad 612. The Examiner contends that the pad is conductive because of the presence of conductive regions 903. Obviously, the Examiner has a reasonable position here.

Nonetheless, the claim still distinguishes.

The claim calls for providing contact to said surface across the pad. The only place a contact is provided between the pad, which the Examiner contends is conductive, and the wafer is via the conductive pads 903. However, because the rest of the polishing pad 612 is an insulator (see column 7, lines 45-48), this is the only contact to the surface of the semiconductor wafer. The other polarity is applied via the copper layer 610 which is spaced back from and does not contact the surface 912.

The claim further calls for providing electrodes "in contact with said surface," said electrodes extending through the pad, said electrodes being of opposite polarity to said contact. Thus, there has to be two items of opposite polarity in contact with the surface of the semiconductor wafer. This does not happen in the cited reference. There is only one contact and the other item, the copper layer 610, applies its field from afar.

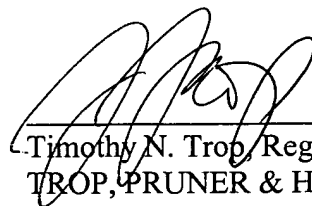
Therefore, reconsideration is respectfully requested.

Claim 1 has been amended to deal with the Section 112 objection. Instead of the reference to contact in the last line, a reference is made to first polarity, which ties back to antecedent basis provided in the second clause of the claim by indicating that the electrical contact is of the first polarity.

Therefore, reconsideration is respectfully requested.

Respectfully submitted,

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Timothy N. Trop, Reg. No. 28,994  
TROP, PRUNER & HU, P.C.  
8554 Katy Freeway, Ste. 100  
Houston, TX 77024  
713/468-8880 [Phone]  
713/468-8883 [Fax]  
Attorneys for Intel Corporation